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Atty. Docket No. JP920000356US1



SHEET

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01-4.2

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1. Name of conveying party(ies):

Mikio Kurihara  
Yoshihisa Yamada  
Fumihisa Hanzawa

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies):

Name: International Business Machines Corporation  
Address: New Orchard Road  
Armonk, NY 10504

Additional name(s) & addresses attached?  Yes  No

3. Nature of conveyance:

Assignment

Execution Date(s): October 18, 2001,  
October 18 2001, October 18, 2001.

4. Patent Application number(s)

09/682,640

Execution Date(s): October 4, 2001,  
October 4, 2001, October 4, 2001.

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Derek S. Jennings  
Address: IBM Corporation  
Intellectual Property Law Dept.  
P.O. Box 218  
Yorktown Heights, NY 10598

6. Total number of applications involved: 1

7. Total fee (37 CFR 3.41): \$40.00

Charge to Deposit Account No.:  
09-0468

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8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of original document.

Derek S. Jennings (Reg. No. 41,473)  
Name of Person Signing

November 6, 2001  
Date

Total Number of pages including cover sheet, attachments, and document: 2

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01/11/2002 AHMED1 00000163 090468 09682640  
40.00 CH  
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# Assignment

Whereas, we

INVENTOR  
AND CITY

(1) Mikio Kurihara  
Yamato-shi, Kanagawa-ken

of 8-7-11, Minamirinkan,  
Japan

(2) Yoshihisa Yamada  
Sagamihara-shi, Kanagawa-ken

of 6-5-8-306, Sagami-ono,  
Japan

(3) Fumihisa Hanzawa  
Machida-shi, Tokyo

of 1978-29, Kanai-chou,  
Japan

TITLE

has invented certain improvements in  
IC HEAT RADIATION STRUCTURE AND DISPLAY DEVICE

DATES THAT  
INVENTORS  
SIGNED THE  
DECLARATION

and executed, respectively, a United States patent application therefor on

- (1) October 4, 2001,
- (2) October 4, 2001,
- (3) October 4, 2001,

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said applications to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed and sealed

CITY AND  
DATE

(1) at YAMATO  
on 10/18 / 2001,

Mikio Kurihara SIGNATURE  
 (Mikio Kurihara) INVENTOR  
 FIRST NAME MIDDLE INITIAL LAST NAME

CITY AND  
DATE

(2) at YAMATO  
on 10/18 / 2001,

Yoshihisa Yamada SIGNATURE  
 (Yoshihisa Yamada) INVENTOR  
 FIRST NAME MIDDLE INITIAL LAST NAME

CITY AND  
DATE

(2) at YAMATO  
on 10/18 / 2001,

Fumihisa Hanzawa SIGNATURE  
 (Fumihisa Hanzawa) INVENTOR  
 FIRST NAME MIDDLE INITIAL LAST NAME